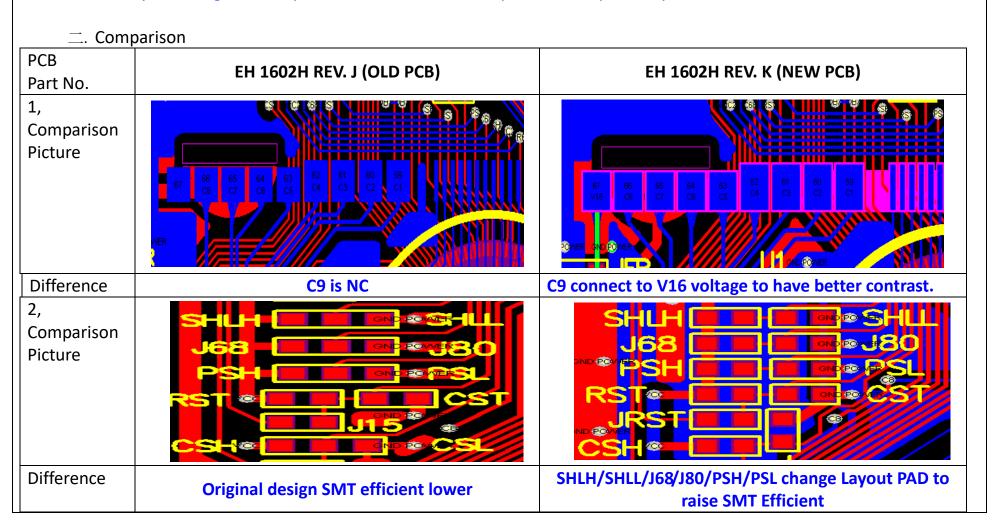
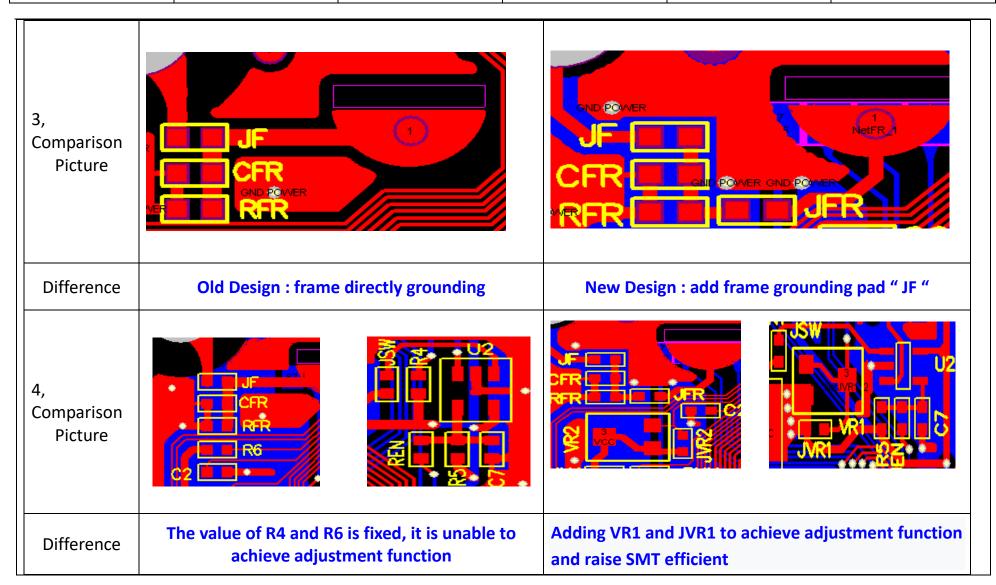
Involved series	WEH001602A PCB Comparison			date	2020.09.01
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#### 一. Reson for Change:

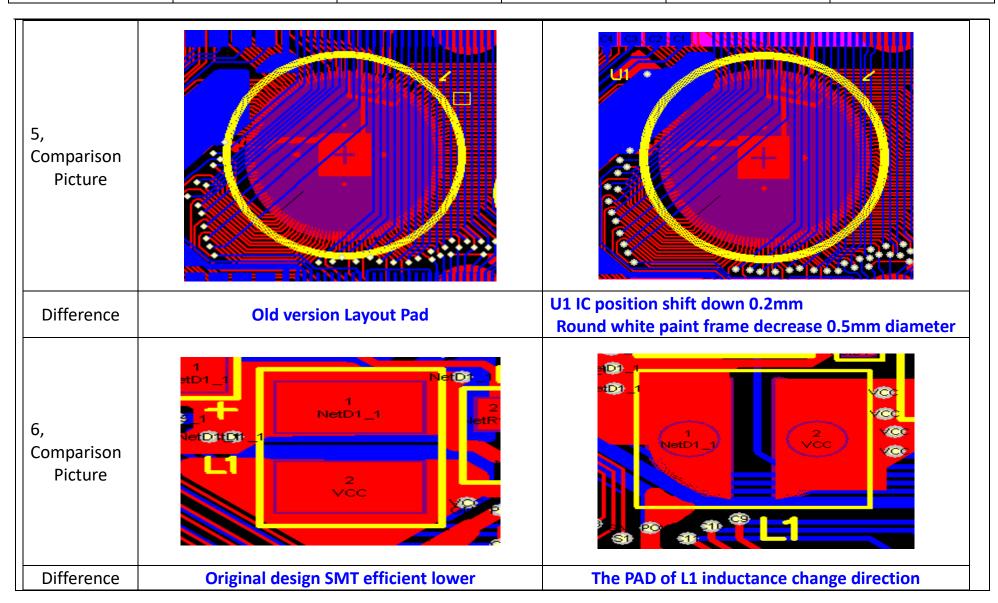
Modify the design of wire path & PAD on the PCB to optimize SMT process yield



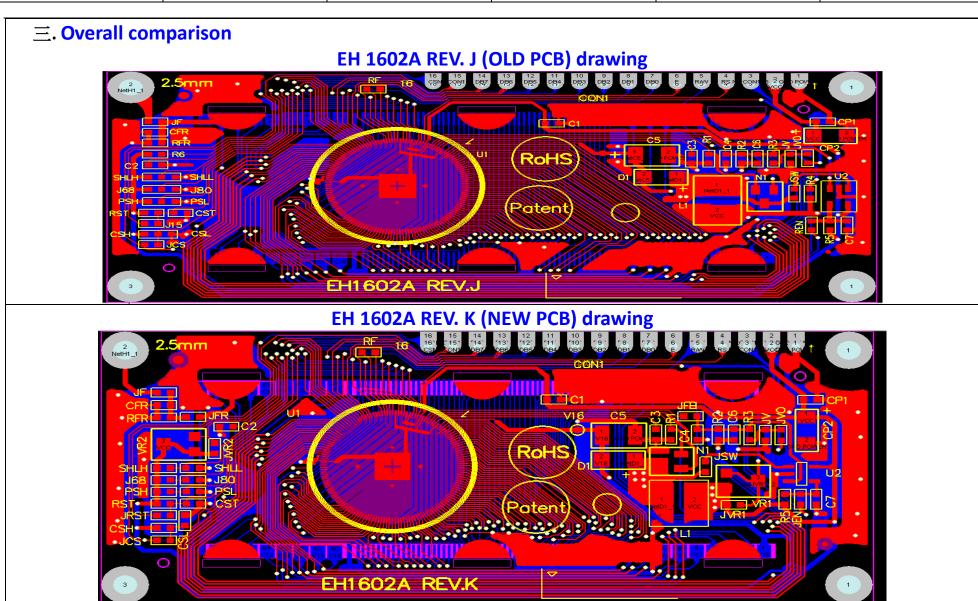
Involved series	WEH001602A PCB Comparison			date	2020.09.01	
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#### 四 · Conclusion

1. 元件位置變更,請確認

the position of components has been changed

2. 模组电性功能与之前一致,电性对客户的使用无影响。

The new version PCB complies with the automation processes and improve yield rate and has better performance. Function & Electrical characteristic remain the same, it won't influences customer using

核准: 翟佩峰 制定:张昱轩